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03-30-1999

FORM PTO-1595
(Rev. 6-93)
OMB No. 0651-0011 (exp. 4/94)

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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

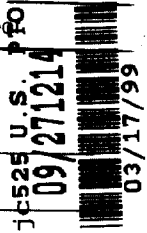
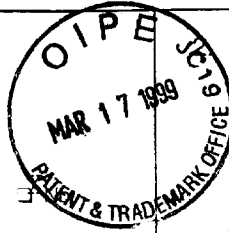
Kuo-Ning CHIANG
Wen-Hwa CHEN
Kuo-Tai TSENG

Additional name(s) of conveying party(ies) attached? Yes No

Name and address of receiving party(ies)

Name: ChipMOS Technologies Inc.

Internal Address: _____



3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other _____

Execution Date: Feb. 25, 1999

Street Address: No. 1, R&D First Road
Science-Based Industrial Park

City: Hsin-Chu State: Taiwan ZIP: R.O.C.

Additional name(s) & address(es) attached? Yes No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: Feb. 25, 1999

A. Patent Application No.(s)

B. Patent No.(s)

09-271214

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Hung Chang LIN

Internal Address: _____

Street Address: 8 Schindler Court

City: Silver Spring State: MD ZIP: 20903

6. Total number of applications and patents involved:

7. Total fee (37 CFR 3.41).....\$ 40.00

Enclosed

Authorized to be charged to deposit account

8. Deposit account number: _____

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Hung Chang LIN

Name of Person Signing

Hung Chang Lin

Signature

March 13, 1999

Date

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PATENT
REEL: 9841 FRAME: 0051

For U.S. and/or Foreign Rights
For U.S. Application or U.S. Patent
By Inventor(s) or Present Owner

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration,

ASSIGNOR :

Kuo-Tai TSENG

(Type or print name(s) of ASSIGNOR(S))

No.579, Din-San Street, San-Min Section, Kao-Hsiang, R.O.C.

Address

the Republic of China.

Nationality

Kuo-Ning CHIANG

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No.5, Lane 1, Alley 192, Yu-Chen Road, Yong-Mei, Tao-Yen, Taiwan, R.O.C.

Address

the Republic of China.

Nationality

Wen-Hwa CHEN

(Type or print name(s) of ASSIGNOR(S))

3F., No. 17, Lane 52, Gin-Cheng First Road, Hsin-Chu, Taiwan, R.O.C.

Address

the Republic of China.

Nationality

(If assignments by person or entity to whom invention was previously assigned and this was recorded in PTO add the following)

Recorded on _____
Reel _____
Frame _____

hereby sells, assigns and transfers to

ASSIGNEE :

ChipMOS Technologies Inc.

(Type or print name of ASSIGNEE)

No.1, R&D First Road, Science-Based Industrial Park, Hsin-Chu, Taiwan, ROC

Address

the Republic of China

Nationality

and the successors, assigns and legal representatives of the ASSIGNEE

(complete one of the following)

- the entire right, title and interest
- an undivided _____ percent(_____ %) interest

for the United States and its territorial possessions

(check the following box if foreign rights are also to be assigned)

- and in all foreign countries

in and to, any and all improvements which are disclosed in the invention entitled :

Stacked Multiple-Chip Module micro Ball Grid Array Packaging.

(check and complete (a), (b), (c) or (d))

and which is found in

- (a) U.S. patent application executed on even date herewith
- (b) U.S. patent application executed on _____
- (c) U.S. application serial no. _____ filed on _____
- (d) U.S. patent no. _____ issued on _____
(also check (e) if foreign application(s) is also being assigned)
- (e) and any legal equivalent there of in a foreign country, including the right to claim priority

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, or substitute, thereof, and as to letters patent any re-issue or re-examination thereof.

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment :

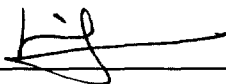
ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly executed and deliver to ASSIGNEE of its legal representatives any and all papers instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I / We have hereunto set hand and seal this

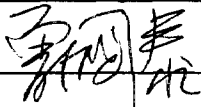
February 25, 1999 (Date of signing).

WARNING : Date of signing must be the same as the date of execution of the application if item (a) was checked above.

Signature of ASSIGNOR(S)



Wen-Shua Chen



If ASSIGNOR is a legal entity complete the following information

Type or print the name of the above person
authorized to sign on behalf of ASSIGNOR

Title

NOTE : No witnessing, notarization or legalization is necessary, if the assignment is notarized or legalized then it will only be prima facie evidence 35USC261, Use next page if notarization is desired.

Notarization of Legalization Page Added.

(Assignment of invention[16-3]—page 2 of 2)